503380203 07/06/2015

EPAS ID: PAT3426825

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Li-Wei Feng	05/25/2015
Shih-Hung Tsai	06/30/2015
Hon-Huei Liu	06/30/2015
Chao-Hung Lin	06/30/2015
Nan-Yuan Huang	06/30/2015
Jyh-Shyang Jenq	06/30/2015

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14792591

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Correspondent Name: WINSTON HSU **Address Line 1:** P.O.BOX 506

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ATTORNEY DOCKET NUMBER: NAUP2513USA

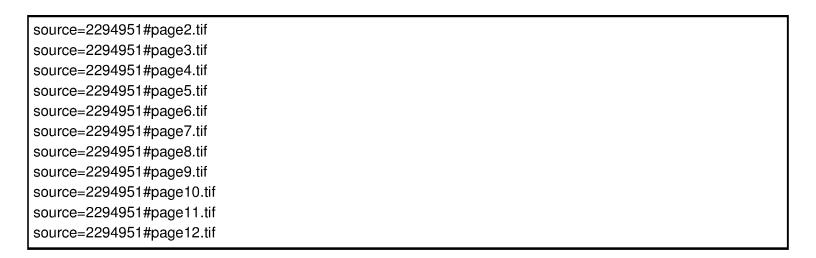
NAME OF SUBMITTER: KATE YEH

SIGNATURE: /KATE YEH/

DATE SIGNED: 07/06/2015

Total Attachments: 12 source=2294951#page1.tif

PATENT 503380203 REEL: 036003 FRAME: 0128



PATENT REEL: 036003 FRAME: 0129

Title of Invention: SEMICONDUCTOR STRUCTURE AND MANUFACTURING METHOD THEREOF

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nu	mber	filed o	on	, or
□ PCT international application	n number	file	d on	_
The above-identified application was	made or authorized	to be made by me.		
I believe that I am the original invent application.	or or an original joint	inventor of a claime	d invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement mad isonment of not more	de in this declaration than five (5) years,	is punishable or both.	
In consideration of the payment by	UNITED MICROECORP.	ELECTRONICS	having a postal ad	dress of
No.3, Li-Hsin Road 2, Science	e-Based Industria	l Park, Hsin-Chu	City 300, Taiwa	n, R.O.C
(referred to as "ASSIGNEE"below) to acknowledged, and for other good are	o I of the sum of One od valuable considera	Dollar (\$ 1.00), the i	receipt of which is h	ereby
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all impo tion and, in and to, a rany continuations, c	overnents which are I Letters Patent to be ontinuation-in-part, o	e disclosed in the e obtained for said divisions, renewals.	
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement o n this assignment;	r encumbrance has l	been or will be mad	e or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe-	ition and said Letters stify as to the same i	Patent and legal eq n any interference, li	uivalents as may be tigation proceeding	octs
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention cessary or desirable	n and said Letters F to carry out the prop	Patent and said coses thereof.	of signing)
Note: An application data sheet (PTC inventive entity, must accompany this				

Page 1 of 12

F#NPO-P0002E-US1201 NPO#NAU-P2513-USA:0 CUST#UMCD-2015-0186 DSC0-104U005713

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Li-Wei Feng	Date:	2015, 5,25	
Signature:	G-Wei Feng			

Page 2 of 12

Title of Invention: SEMICONDUCTOR STRUCTURE AND MANUFACTURING METHOD THEREOF

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I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, an	nd to any and all improvements w tion and, in and to, all Letters Par r any continuations, continuation-	hich are disclosed in the tent to be obtained for said in-part, divisions, renewals,	
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbrar n this assignment;	nce has been or will be mad	le or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Patent and stify as to the same in any interfe	legal equivalents as may be erence, litigation proceeding	е
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention and said lecessary or desirable to carry out	Letters Patent and said the proposes thereof.	of signing)
Note: An application data sheet (PTC inventive entity, must accompany thi			

Page 3 of 12

F#NPO-P0002E-US1201

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Shih-Hung Tsai	Date:	JUN 3 0 2015	
Signature:	Shop - Hung Trai			

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NPO#NAU-P2513-USA:0 CUST#UMCD-2015-0186

Title of Invention:

SEMICONDUCTOR STRUCTURE AND MANUFACTURING METHOD THEREOF

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I hereby covenant that no assignmer entered into which would conflict witl	nt, sale, agreement o h this assignment;	r encumbrance has	been or will be r	nade or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters estify as to the same i	Patent and legal eq n any interference, l	uivalents as ma	ly be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention ecessary or desirable	on and said Letters F to carry out the prop	Patent and said poses thereof.	Date of signing)
Note: An application data sheet (PTC inventive entity, must accompany thi				

Page 5 of 12

LEGAL NA	WE OF INVENTOR(ASSIGNOR)			
Inventor:	Hon-Huei Liu	Date:	JUN 3 0 2015	
Signature:	Upon this is			

Page 6 of 12

Title of Invention: SEMICONDUCTOR STRUCTURE AND MANUFACTURING METHOD THEREOF

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l hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or e n this assignment;	ncumbrance has	been or will	be made or
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representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention a ecessary or desirable to	and said Letters carry out the pro	Patent and s	aid of. (Date of signing)
Note: An application data sheet (PTC				

Page 7 of 12

NPO#NAU-P2513-USA:0 CUST#UMCD-2015-0186

LEGAL NAME OF INVENTOR(ASSIGNOR)			Thus.
Inventor:	Chao-Hung Lin	Date:	JUN 3 0 2015
Signature:	Chao - Hung Lin		

Page 8 of 12

NPO#NAU-P2513-USA:0 CUST#UMCD-2015-0186

Title of Invention:

SEMICONDUCTOR STRUCTURE AND MANUFACTURING METHOD THEREOF

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I further covenant that ASSIGNEE w and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	ition and said Letters Patent and stify as to the same in any interfe	legal equivalents as may be rence litigation proceeding	;
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention and said L cessary or desirable to carry out	etters Patent and said	signing)
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent), including s form. Use this form for <u>each add</u>	naming the entire litional inventor.	

Page 9 of 12

LEGAL NAI	ME OF INVENTOR (ASSIGNO		_		
Inventor:	Nan-Yuan Huang		Date:	JUN 3 0 2015	
Signature:	Nau-Yuan	Huang	- Milanigue		

Page 10 of 12

NPO#NAU-P2513-USA:0 CUST#UMCD-2015-0186

Title of Invention:

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I hereby covenant that no assignment entered into which would conflict with	t, sale, agreement or ei this assignment;	ncumbrance f	nas beer	or will b	e made or	
I further covenant that ASSIGNEE wil and documents relating to said invent known and accessible to I and will tes related thereto and will promptly exec	ion and said Letters Pa tify as to the same in a	itent and lega nv interferend	ıl equiva ce. litigat	lents as r	nav be	
representatives any and all papers, in maintain, issue and enforce said appli equivalents thereof which may be ned IN WINTNESS WHEREOF, I have he	ication, said invention a sessary or desirable to	and said Lette carry out the	rs Pater	nt and sai s thereof.	id (Date of signing	g)
Note: An application data sheet (PTO)	/SB/14 or equivalent), i	ncluding nam	ing the	entire		

Page 11 of 12

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Jyh-Shyang Jenq

Date:

JUN 3 0 2015

Signature:

gang gripsly

Page 12 of 12

F#NPO-P0002E-US1201 DSC0-104U005713

RECORDED: 07/06/2015 REEL:

NPO#NAU-P2513-USA:0

CUST#UMCD-2015-0186